

ABSTRACT OF THE DISCLOSURE

A structure for preventing MMICs (Monolithic Microwave Integrated Circuits) from the deterioration in the high-frequency transmission characteristics thereof, which is resulted from mechanical pressure applied to the pads during the wire-bonding thereto for external connection. The structure includes a groove provided in the surface of the interlayer insulation film around each of the pads. The line conductor for transmitting high-frequency signals is free from the peeling off or bending thereof, which is caused by the deformation in the interlayer insulation films during when the mechanical pressure applied to the pads, and thus, the change in the transmission characteristics of the line conductor can be minimized, and the reliability of MMICs can be improved.

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